



Material Composition Declaration

Package Information

Package	Package Weight (mg)	Terminal Finish	MSL Rating
SMC	210	Matte Tin (Sn)	1

Product Group

Type No.	Description
SK32 – SK3200	Diode Schottky 3A 20V – 200V
SK52 – SK5200	Diode Schottky 5A 20V – 200V
SK82 – SK8200	Diode Schottky 8A 20V – 200V
ER3A – ER3J	Diode Superfast 3A 50V – 600V
ER5A – ER5J	Diode Superfast 5A 50V – 600V
UF3A – UF3M	Diode Ultrafast 3A 50V – 1000V
UF5A – UF5M	Diode Ultrafast 5A 50V – 1000V
FR3A – FR3M	Diode Fast 3A 50V – 1000V
FR5A – FR5M	Diode Fast 5A 50V – 1000V
S3A – S3M	Diode Standard 3A 50V – 1000V
S5A – S5M	Diode Standard 5A 50V – 1000V
S10A – S10M	Diode Standard 10A 50V – 1000V
1.5SMCJ Series	Diode TVS 1500W
3.0SMCJ Series	Diode TVS 3000W
5.0SMCJ Series	Diode TVS 5000W
1SMC5333B – 1SMC5388B	Diode Zener 5W

Component	Material	Substance	CAS No.	Material Mass (%)	Material Mass (mg)	Component Mass (%)	Component Mass (mg)	PPM
Die	Doped Silicon*	Si	7440-21-3	100.00	10.40	4.95	10.40	49524
Die Attach	Solder Alloy	Pb	7439-92-1	92.50	3.89	2.00	4.20	18500
		Sn	7440-31-5	5.00	0.21			1000
		Ag	7440-22-4	2.50	0.11			500
Leadframe	Copper Alloy	Cu	7440-50-8	97.50	86.09	42.05	88.30	409964
		Fe	7439-89-6	2.40	2.12			10091
		Zn	7440-66-6	0.10	0.09			420
Plating	Matte Tin	Sn	7440-31-5	100.00	2.10	1.00	2.10	10000
Encapsulation	EMC	Silica	7631-86-9	74.91	78.66	50.00	105.00	374550
		Epoxy Resin	29690-82-2	23.13	24.29			115650
		Sb ₂ O ₃	1309-64-4	0.98	1.03			4900
		Brominated Epoxy Resin	6386-73-8	0.98	1.03			4900

Tolerance ±10%

*Dopant and metallization of the silicon die are not reported in this statement where their concentration is less than the minimum reportable level per EIA JIG-101.

Data disclosed herewith is approximate and is based on information from suppliers surveys, Material Safety Datasheet, engineering calculations and measurements. Won-Top Electronics(WTE) has checked all information carefully and believes it to be correct and accurate. However, WTE cannot assume any responsibility for inaccuracies. WTE reserves the right to change any or all information herein without further notice.

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronics Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBD), Bis(2-ethylhexyl) Phthalate (DEHP), Butyl Benzyl Phthalate (BBP), Dibutyl Phthalate (DBP) and Diisobutyl Phthalate (DIBP) to 0.1%(1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01%(100 PPM) in homogeneous materials of electronics products.

The product group listed above and the homogenous materials are compliant with the Directive 2011/65/EU and amending EU Directive 2015/863/EU. WTE warrants that all its packing, components and/or products supplied to the Customer and/or its affiliated companies or designated contractors do not contain these hazardous substances in quantity levels higher than or equal to the thresholds to these directives.

Exemptions as declared for the directive are:

- 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
- 7(c)-I Lead in glass (applicable for glass passivated silicon die).